

REMARKS

In view of the above amendments and following remarks, reconsideration and further examination are requested.

In section 10 on pages 6-9 of the Office Action mailed August 29, 2003, claims 21-35 as pending at that time were rejected under 35 U.S.C. § 103(a) as being unpatentable over Applicant's admitted prior art in view Ferlier et al. In the initial paragraph on page 9 of that Office Action, the motivation for modifying Applicant's admitted prior art in view of Ferlier et al. was stated to be to provide the wire of Applicant's admitted prior art with a high quality marking.

On November 24, 2003, an interview was conducted between Applicant's undersigned representative and Examiner Mayo. During this interview proposed amendments to the claims were discussed, and as stated by the Examiner in the Interview Summary reflecting the results of this interview, these proposed amendments would overcome the prior art of record.

Accordingly, on December 1, 2003, a response was filed which amended the claims in accordance with the proposed amendments discussed during the interview that the Examiner indicated would overcome the prior art of record. And, after non-entry of this response due the proposed amendments raising new issues, an RCE was filed on January 16, 2004, so as to have this response considered by the Examiner.

On March 1, 2004, an Office Action in response to this RCE was furnished by the Patent Office, and this Office Action continued to reject the claims under 35 U.S.C. § 103(a) as being unpatentable over Applicant's admitted prior art in view Ferlier et al., with the stated motivation being to provide the wire of Applicant's admitted prior art with a high quality marking, i.e. the same motivation that was presented in the Office Action mailed August 29, 2003.

Accordingly, on May 26, 2004, Applicant's undersigned representative discussed the above-identified application with Examiner Mayo via telephone. During this interview, Applicant's undersigned representative pointed out that the currently pending claims are the same as those that were said to be allowable by the Examiner, during the interview conducted on November 24, 2003, over the same references currently being applied by the Examiner. Examiner Mayo expressed that he believes claims 12-29 are properly rejected as being obvious over a combination of Applicant's

admitted prior art and Ferlier et al., but expressed that he would reconsider his position upon the filing of a response.

Also during the aforementioned telephonic interview, Applicant's undersigned representative pointed out that the admitted prior art as shown in Figure 7 does not include the "empty space" as recited in claim 30. Examiner Mayo stated that the rejection of claim 30 would not be maintained upon the filing of a response which includes a statement that the admitted prior art as depicted in Figure 7 does not in fact include the empty space as recited in claim 30.

Thus, in view of the telephonic interview conducted May 26, 2004, the following is presented.

With regard to independent claim 12, this claim recites

An enameled wire comprising:
a copper or copper alloy core wire;
an insulating coated layer covering and contacting
said core wire; and
a melting layer covering said insulating coated layer,
wherein said insulating coated layer is for efficiently
absorbing a laser beam so as to be melted and stripped away
upon absorbing the laser beam such that said core wire is able
to be soldered.

It is appreciated that in Figure 6 of the instant application, i.e. Applicant's admitted prior art, coated layer 1c is shown to cover and contact core wire 1b, and in Ferlier et al. layer 14 is stated to "facilitate laser beam absorption"; however, for the same reasons as expressed in the amendment filed December 1, 2003, and forming a part of the RCE filed January 16, 2004, a combination of Applicant's admitted prior art and Ferlier et al. would not result in the invention as recited in claim 12.

In this regard, the insulating coated layer 1c as shown in Figure 6 is to absorb a laser beam so as to be melted and stripped away upon the laser beam penetrating the insulating coated layer such that the core wire can be soldered. To the contrary, the insulating coated layer in Ferlier et al., i.e. (20, 21), 14 or 24, is to absorb a laser beam so as to prevent the laser beam from penetrating therethrough such that the insulating coated layer remains, whereby provided is a contrast of the insulating coated layer relative to the outer layer 19, 13 or 23. Accordingly, because of the different purposes for which the insulating coated layers of Ferlier et al. and Applicant's admitted prior art

absorb a laser beam, there would have been no motivation or suggestion to have combined this prior art so as to arrive at the invention as recited in claim 12.

With regard to independent claim 21, the claim recites

A method of soldering an enameled wire, comprising:
irradiating a laser beam to an enameled wire that includes
(i) a copper or copper alloy core wire,
(ii) an insulating coated layer covering said core wire,
said insulating coated layer being for efficiently absorbing said
laser beam so as to be melted and stripped away upon absorbing
said laser beam, and
(iii) a melting layer covering said insulating coated layer,
thereby melting and stripping away at least part of said insulating
coated layer and soldering said core wire to a soldering portion.

For reasons analogous to those expressed above with regard to claim 12, claim 21 also defines around a combination of Applicant's admitted prior art and Ferlier et al., since there would have been no motivation or suggestion to combine the teachings of this prior art so as to arrive at the invention as recited in claim 21 due to the different purposes for which the insulating coated layers of Ferlier et al. and the admitted prior art absorb a laser beam as discussed above.

Additionally, to have modified Applicant's admitted prior art by not having the laser beam penetrate completely through the insulating coated layer, as taught by Ferlier et al., would destroy Applicant's admitted prior art of its intended purpose of soldering the core wire to a soldering portion by having the laser beam penetrate through the insulating coated layer.

And, with regard to independent claim 30, in accordance with the telephonic interview of May 26, 2004, it is respectfully submitted this claim is allowable over Applicant's admitted prior art in view of Ferlier et al., because claim 30 requires that "said molded resin body includes an empty space underneath at least a portion of said soldering portion". This empty space is represented by reference numeral 26a as shown in Figure 4, for example. The molded resin body as depicted in Figure 7 does not include such an empty space. Accordingly, claim 30 is also not obvious over a combination of Applicant's admitted prior art and Ferlier et al.

Thus, claims 12-36 are allowable.

In view of the above amendments and remarks, it is respectfully submitted that the present application is in condition for allowance and an early Notice of Allowance is earnestly solicited.

If after reviewing this Amendment, the Examiner believes that any issues remain which must be resolved before the application can be passed to issue, the Examiner is invited to contact the Applicant's undersigned representative by telephone to resolve such issues.

Respectfully submitted,

Kenichi AJIKI

By:



Joseph M. Gorski
Registration No. 46,500
Attorney for Applicant

JMG/edg
Washington, D.C. 20006-1021
Telephone (202) 721-8200
Facsimile (202) 721-8250
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